

Title (en)
COOLING DEVICE

Title (de)
KÜHLEINRICHTUNG

Title (fr)
SYSTEME DE REFROIDISSEMENT

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Application
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Abstract (en)
[origin: WO2005088713A1] The invention relates to a cooling device for an electronic unit, in particular, a power supply device, comprising a cooling body (1), arranged in an essentially airtight sealed housing of the electronic unit, through which a cooling medium may flow, mounted on the heat generator (12) which is in particular electronic components, releasing the heat to the cooling body (1) by contact transmission, whereby additional heat exchange means (9.1, 9.2), for cooling the air enclosed in the housing, are connected to the cooling body (1) with a thermal conducting connection and arranged on said cooling body (1). Such a cooling device can be produced with a compact construction with effective heat extraction.

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Citation (search report)
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